

CS98-070B
ORIGINALY FILED
COPY OF PAPERS



COPY OF PAPERS
ORIGINALY FILED

Feb. 28, 2002

RECEIVED
MAR 21 2002
TECNOLOGY CENTER 2800

2815
#6/C
Amend
BLL
4-82

To: Commissioner of Patents and Trademarks
Washington, D.C. 20231
ATTN: Group Art Unit 2815 J. R. Diaz

From: Stephen B. Ackerman, Reg. No. 37,761
20 McIntosh Drive
Poughkeepsie, N. Y. 12603

Serial No. 09/764,242 01/19/2001

Wong

A FILL PATTERN IN KERF AREAS TO PREVENT LOCALIZED
NON-UNIFORMITIES OF INSULATING LAYERS AT DIE
CORNERS ON SEMICONDUCTOR SUBSTRATES

Group Art Unit: 2815 J. R. Diaz

RESPONSE TO PATENT OFFICE ACTION

Dear Sir or Madam:

The Commissioner is hereby authorized to charge payment
of any additional fees involved with added Claims and the
like to Deposit Account No. 19-0033.

In response to Office Action dated Dec. 5, 2001, please
amend the above identified application for patent as
follows, and please consider the following remarks.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the U. S. Postal Service as first class mail
in an envelope addressed to: Commissioner of Patents and
Trademarks, Washington, D.C. 20231, on March 5, 2002.

Stephen B. Ackerman, Reg. No. 37,761

Signature

Date 3/5/02